Customer No.: 31561 Application No.: 10/605,325 Docket No.: 11467-US-PA

#### **AMENDMENTS**

### In The Claims

- 1. (original) A liquid crystal display, comprising:
- two substrates, being spaced apart in parallel;
- an enclosed wall structure, provided in between said two substrates, wherein the enclosed wall structure and said two substrates form a first enclosed space;
- a sealant, formed outside said enclosed wall structure between said two substrates, wherein said sealant and said two substrates form a second enclosed space;
- a liquid crystal layer, formed in said first enclosed space between said two substrates; and
- at least a thin film transistor, being formed in said first enclosed space on one of said two substrates.
- 2. (original) The liquid crystal display as recited in claim 1, wherein said enclosed wall structure comprises a conductive wall.
- 3. (currently amended) The liquid crystal display as recited in claim 12, wherein said conductive wall serves to conduct said two substrates.
- 4. (currently amended) The liquid crystal display as recited in claim 1, wherein a plurality of conductive walls for conducting said two substrates are provided on said substrate that has said thing thin film transistors.
  - 5. (withdrawn) The liquid crystal display as recited in claim 1, wherein said enclosed

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wall structure comprises an insulating wall.

6. (withdrawn) The liquid crystal display as recited in claim 1, wherein said enclosed

wall and said sealant are bonded.

7. (withdrawn) The liquid crystal display as recited in claim 1, wherein said enclosed

wall and said sealant are spaced apart.

8. (original) The liquid crystal display as recited in claim 1, wherein said sealant

comprises a light hardening adhesive.

9. (withdrawn) A method of manufacturing a liquid crystal display, which

comprises:

providing a first substrate;

forming a first conductive layer on said first substrate;

forming a first insulating layer on said first conductive layer;

forming a second conductive layer on said first insulating layer,

wherein between forming said first conductive layer on said first substrate and

forming said second conductive layer on said first insulating layer and after forming said

second conductive layer on said first insulating layer further comprises forming an

enclosed wall on periphery of surface of said first substrate;

providing a second substrate;

forming a sealant on either a surface of said first substrate or a surface of said second

substrate, wherein said sealant is located relatively outside said enclosed wall;

bonding said first substrate and said second substrate together; and

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irradiating said sealant;

10. (withdrawn) The method of manufacturing a liquid crystal display as recited in

claim 9, further comprising a plurality of conductive walls that are formed on said first

substrate so as to conduct to said second substrate.

11. (withdrawn) The method of manufacturing a liquid crystal display as recited in

claim 9, wherein the step of forming said enclosed wall on periphery of said first

substrate surface further comprise:

controlling a first mask to at least cover said conductive layers and said insulating

layers that are formed;

controlling a second mask;

superimposing said first mask and said second mask on said first substrate;

continuing deposition; and

removing said first mask and said second mask in order to form said enclosed wall

on surface periphery of said first substrate.

12. (withdrawn) The method of manufacturing a liquid crystal display as recited in

claim 11, wherein said first mask configures patterns so as to from said plurality of

conductive walls on said first substrate to conduct to said second substrate.

13. (withdrawn) The method of manufacturing a liquid crystal display as recited in

claim 11, wherein a third mask that is patterned is further controlled to perform

conductive layer deposition in order to form said plurality of conductive walls on said

first substrate so as to conduct to said second substrate.

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14. (withdrawn) The method of manufacturing a liquid crystal display as recited in

claim 9, wherein the step of forming said enclosed wall on surface periphery of said first

substrate is performed after the step of forming said first conductive layer on said first

substrate and before the step of forming said first insulating layer on said first conductive

layer, and said enclosed wall that comprises a conductive wall which forms an enclosed

space when bonded to said first substrate and said second substrate as well as conducts to

said second substrate upon contact.

15. (withdrawn) The method of manufacturing a liquid crystal display as recited in

claim 9, wherein the step of forming said enclosed wall on surface periphery of said first

substrate is performed after the step of forming said first insulating layer on said first

conductive layer and before the step of forming said second conductive layer on said first

insulating layer, and said enclosed wall comprises an insulating wall which forms an

enclosed space when bonded to said first substrate and said second substrate.

16. (withdrawn) The method of manufacturing a liquid crystal display as recited in

claim 9, wherein the step of forming said enclosed wall on surface periphery of said first

substrate is performed after the step of forming said second conductive layer on said first

insulating layer, and said enclosed wall comprises a conductive wall which forms an

enclosed space when bonded to said first substrate and said second substrate as well as

conducts to said second substrate upon contact.

17. (withdrawn) The method of manufacturing a liquid crystal display as recited in

claim 9, further comprising a step of forming a second insulating layer on said second

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conductive layer and forming said enclosed wall on surface periphery of said first

substrate, wherein said step is performed after the step of forming said first conductive

layer on said first substrate and before or after the step of forming said second insulating

layer on said second conducting layer.

18. (withdrawn) The method of manufacturing a liquid crystal display as recited in

claim 17, wherein the step of forming the enclosed wall on surface periphery of the first

substrate is performed after the step of forming said second insulating layer on said

second conductive layer, and said enclosed wall comprises an insulating wall which

forms an enclosed space when bonded to said first substrate and said second substrate.

19. (withdrawn) The method of manufacturing a liquid crystal display as recited in

claim 17, further comprising a step of forming a third conductive layer on said second

insulating layer and forming said enclosed wall on surface periphery of said first

substrate, wherein said step is performed after the step of forming said first conductive

layer on said first substrate and before or after the step of forming said third conductive

layer on said second insulating layer.

20. (withdrawn) The method of manufacturing a liquid crystal display as recited in

claim 19, wherein the step of forming said enclosed wall on surface periphery of said first

substrate is performed after the step of forming said third conductive layer on said second

insulating layer, and said enclosed wall comprises a conductive wall which forms an

enclosed space when bonded to said first substrate and said second substrate as well as

conducts to said second substrates upon contact.

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21. (withdrawn) A method of manufacturing a liquid crystal display, which comprises:

providing a first substrate;

forming a first conductive layer on said first substrate;

forming a first insulating layer on said first conductive layer;

forming a second conductive layer on said first insulating layer,

wherein between forming said first conductive layer on said first substrate and forming said second conductive layer on said first insulating layer as well as after forming said second conductive layer on said first insulating layer, further comprises forming a plurality of conductive walls on surface of said first substrate;

providing a second substrate;

forming a sealant on either surface of said first substrate or surface of said second substrate;

forming a liquid crystal layer on one of said first substrate and second substrate within said sealant;

bonding said first substrate and said second substrate together; and irradiating said sealant.

22. (withdrawn) The method of manufacturing a liquid crystal display as recited in claim 21, wherein forming said conductive walls on said first substrate further comprises:

controlling a mask to at least cover said conductive layers and said insulating layers

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that are formed.

continuing deposition; and

removing the mask, so as to form said conductive walls on said first substrate.

23. (withdrawn) The method of manufacturing a liquid crystal display as recited in

claim 21, wherein the step of forming said conductive walls on said first substrate is

performed after the step of forming said first conductive layer on said first substrate and

before the step of forming said first insulating layer on said first conductive layer as well

as conducts to said second substrate upon contact.

24. (withdrawn) The method of manufacturing a liquid crystal display as recited in

claim 21, wherein the step of forming said conducting walls on said first substrate is

performed after the step of forming said second conductive layer on said first insulting

layer as well as conducts to said second substrate upon contact.

25. (withdrawn) The method of manufacturing a liquid crystal display as recited in

claim 21, further comprising the step of forming a second insulating layer on said second

conductive layer.

26. (withdrawn) The method of manufacturing a liquid crystal display as recited in

claim 25, further comprising a step of forming a third conductive layer on said second

insulating layer and forming said enclosed wall on surface periphery of said first

substrate, wherein said step is performed after the step of forming said first conductive

layer on said first substrate and before or after the step of forming said third conductive

layer on said second insulating layer.

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27. (withdrawn) The method of manufacturing a liquid crystal display as recited in claim 26, wherein the step of forming said conductive walls on said first substrate is performed after the step of forming said third conductive layer and said second insulating layer as well as conducts to said second substrate upon contact.

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